

View Online at <https://aerobasegroup.com/nsn/5910-01-388-5892>

Body Style:

Chip type

Reliability Indicator:

Established

Reliability Failure Rate Level In Percent:

0.100

Body Length:

Between 0.090 inches and 0.145 inches

Body Width:

0.110 inches

Body Height:

Between 0.030 inches and 0.102 inches

Schematic Diagram Designator:

No common or grounded electrode (s)

Insulation Resistance At Maximum Operating Temp:

100000.0 megohms

Capacitance Value Per Section:

4.700 picofarads single section

Nonderated Operating Temp:

Between -55.0 degrees celsius and 125.0 degrees celsius

Temperature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius:

90.0 single section

Nonderated Continuous Voltage Rating And Type Per Section:

500.0 dc single section

Tolerance Of Temperature Coefficient Per Section In Ppm Per Deg Celsius:

-20.0/+20.0 single section

Tolerance Range Per Section:

-0.25/+0.25 picofarads single section

Case Material:

Ceramic

Insulation Resistance At Reference Temp:

100000.0 megohms

Dissipation Factor At Reference Temperature In Percent:

0.050

Reference Temperature At Which Rated:

25.0 degrees celsius

Terminal Surface Treatment:

Solder

Test Data Document:

81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).

Terminal Type And Quantity:

2 bonding pad

Specification Data:

81349-mil-c-55681/4 government specification

Shelf Life:

N/a

Unit Of Measure:

--

Demilitarization:

No

Fiig:

A010b0